



SOT323

plastic, surface-mounted package; 3 terminals; 1.3 mm pitch;
2 mm x 1.25 mm x 0.95 mm body

9 January 2017

Package information

1. Package summary

Dimensions (mm)	2 x 1.25 x 0.95
Terminal position code	D (double)
Package type descriptive code	SC-70
Package outline version code	SOT323
Manufacturer package code	SOT323
Package type industry code	SC-70
Package outline version description	plastic, surface-mounted package; 3 terminals; 1.3 mm pitch; 2 mm x 1.25 mm x 0.95 mm body
Package style descriptive code	SOT (small outline transistor)
Package body material type	P
JEITA package outline code	SC-70
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	SC18_1999_CHAPTER_5_2
Mounting method type	S (surface mount)
Generic mounting and soldering information	AN10365_3
Wave soldering footprint	SOT323_fw
Package life cycle status	REL
Major version date	18-9-2008
Minor version date	11-5-2012
Security status	COMPANY PUBLIC
Modified date	28-11-2012
Issue date	16-3-2006
Web publication date	28-11-2012
Initial web publication date	11-3-2011
Customer specific indicator	N
Maturity	Product
Package author	Nair Deepa
Package approver	Nair Deepa

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A	seated height	0.8	-	0.95	1.1	mm
D	package length	1.8	-	2	2.2	mm
E	package width	1.15	-	1.25	1.35	mm



plastic, surface-mounted package; 3 terminals; 1.3 mm pitch; 2 mm x 1.25 mm x 0.95 mm body

Symbol	Parameter		Min	Typ	Nom	Max	Unit
e	nominal pitch		-	-	1.3	-	mm
n ₂	actual quantity of termination		-	-	3	-	

2. Package outline

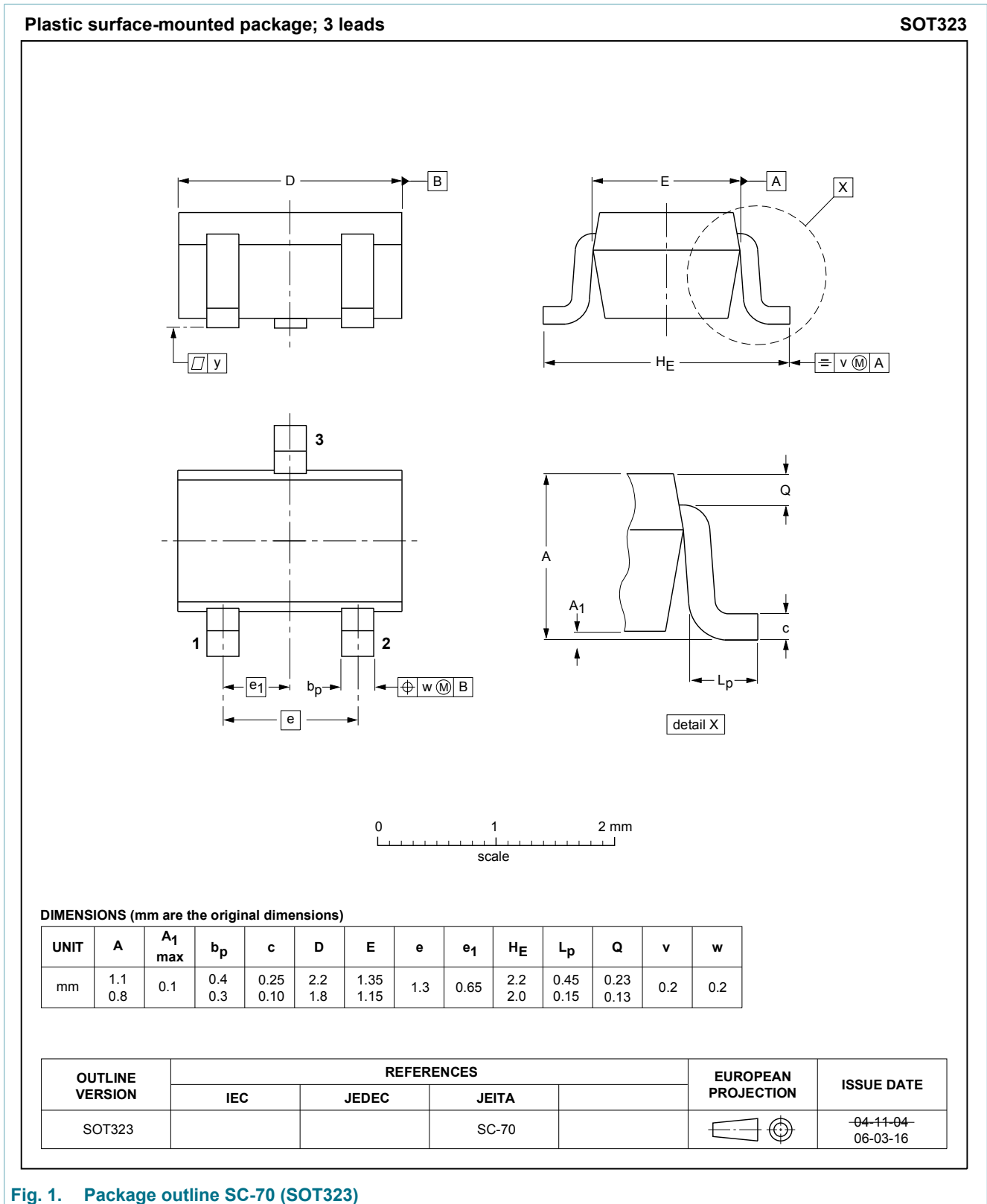


Fig. 1. Package outline SC-70 (SOT323)

3. Soldering

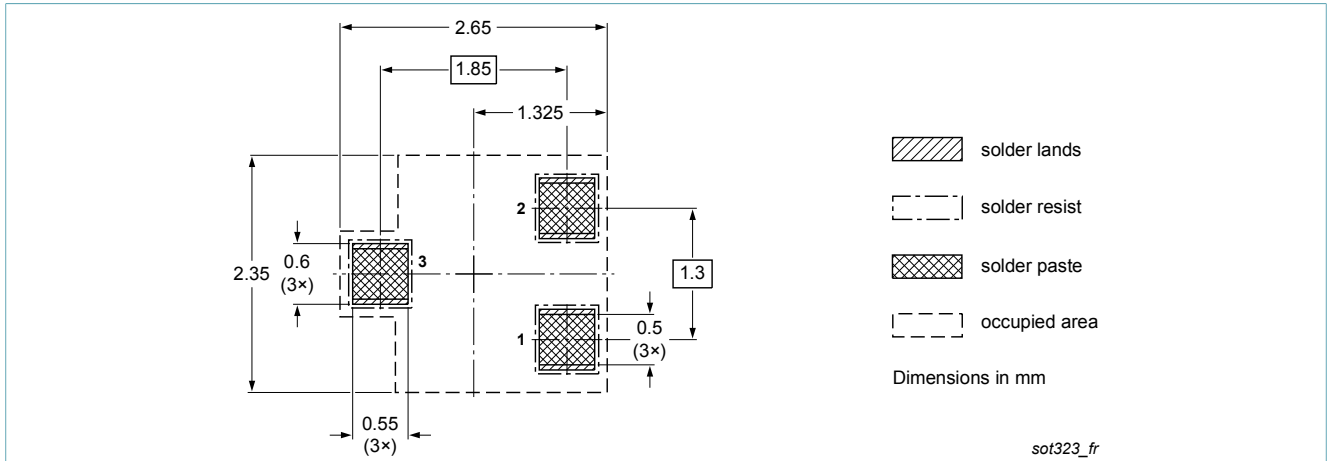


Fig. 2. Reflow soldering footprint for SC-70 (SOT323)

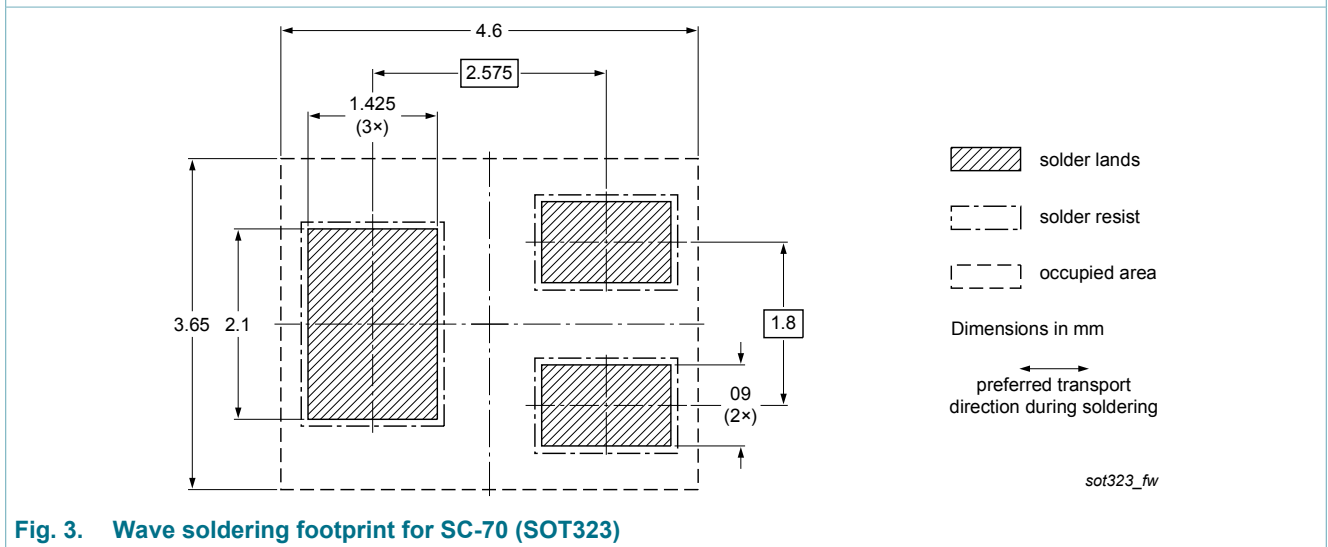


Fig. 3. Wave soldering footprint for SC-70 (SOT323)

4. Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

plastic, surface-mounted package; 3 terminals; 1.3 mm pitch; 2 mm x 1.25 mm x 0.95 mm body

5. Contents

1. Package summary.....	1
2. Package outline.....	3
3. Soldering.....	4
4. Legal information.....	5

© NXP Semiconductors N.V. 2017. All rights reserved

For more information, please visit: <http://www.nxp.com>
For sales office addresses, please send an email to: salesaddresses@nxp.com
Date of release: 9 January 2017
